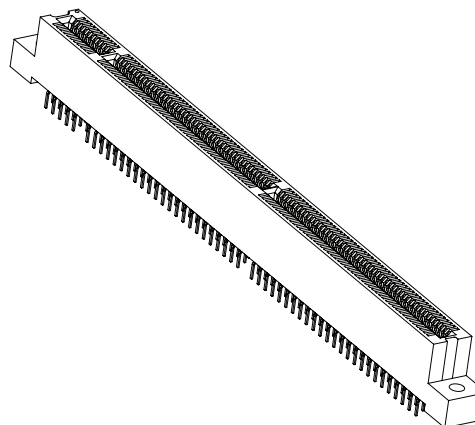


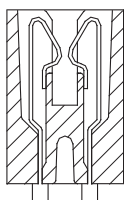


SPECIFICATIONS

- Accommodates $.062" \pm .008"$ [1.57 mm $\pm$ 0.20 mm] PC board
(Consult factory for other board thicknesses)
- PPS or PA9T insulator
- Molded-in key available
- High reliability/high cycle hairpin bellow contacts
- 1 Amp current rating per contact for contacts fully energized
- UL Flammability Rating: 94V-0



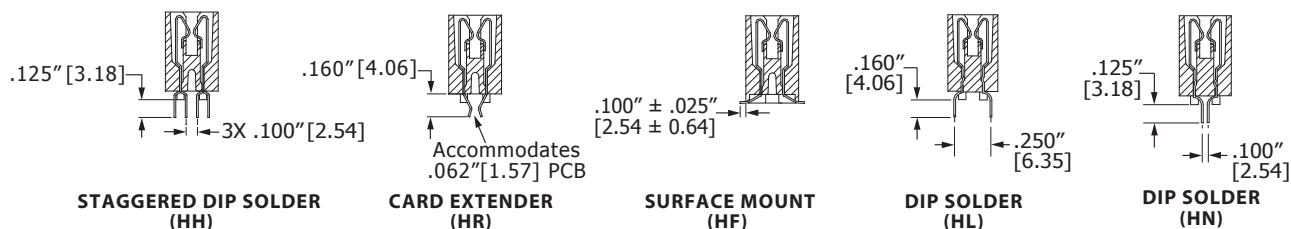
READOUT



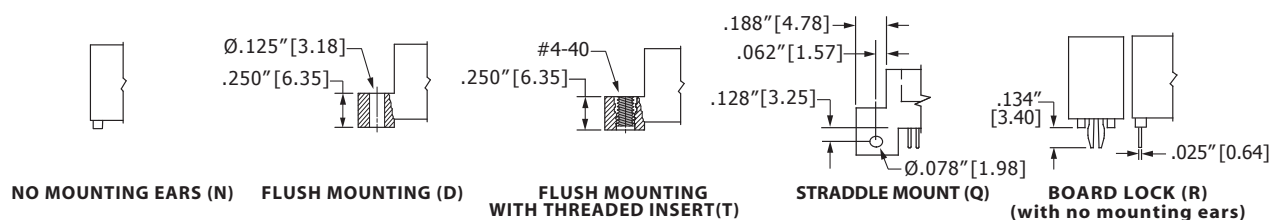
DUAL (D)

TERMINATION TYPE

Consult Factory for PC Board Layouts



MOUNTING STYLE



**.050" [1.27 mm] Contact Centers, .610" [15.49 mm] Insulator Height,
[MCA] Dip Solder/Card Extender/SMT**

Industry Standard Part

PART NUMBER OPTIONS

MATERIALS (INSULATOR/CONTACT)

G = PA9T/Phosphor Bronze

R = PPS/Phosphor Bronze

J = PA9T/Beryllium Copper

A = PPS/Beryllium Copper

Refer to Page 7 for Operating/Processing Temperatures

CONTACT FINISH - RoHS Compliant

All platings are Lead Free and have .000050" Nickel underplate

Contact Surface

Termination

B = .000010" Gold

.000100" Pure Tin, Matte

C = .000030" Gold

.000100" Pure Tin, Matte

CONTACT CENTERS

$$B = .050'' [1.27 \text{ mm}]$$

NUMBER OF CONTACT POSITIONS

56, 66, 91, 106

G B B 56 D HH D-S578

— **MODIFICATION** (Consult Factory)

-S578 = Card Slot Barriers With Guide Posts

-S621 = Card Slot Barriers Without Guide Posts

—MOUNTING STYLE

N = No Mounting

D = Flush Mounting

T = Flush Mounting With Threaded Insert

Q = Straddle Mount

(Card Extender Only - Consult Factory)

R = Metal Board Lock

—TERMINATION TYPE

HH = Staggered Dip Solder

HR = Card Extender

HF = Surface Mount

HL = .250" [6.35] X .160" [4.06] Dip Solder

HN = .100" [2.54] X .125" [3.18] Dip Solder

—READOUT

D = Dual

DIMENSIONS Dimensions in [] are in millimeters, all others are in inches.

